

2826



PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

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In re application of

Docket No: Q67930

Hiroki TAKEUCHI, et al.

Appln. No.: 10/026,454

Group Art Unit: 2826

Confirmation No.: 1274

Examiner: Alexander O. Williams

Filed: December 27, 2001

August 26, 2002 (Monday)

For: EMBEDDING RESIN AND WIRING
SUBSTRATE USING THE SAME

#9/a
9/3/02
Juro

RESPONSE TO RESTRICTION REQUIREMENT AND AMENDMENT

Commissioner for Patents
Washington, D.C. 20231

Sir:

In timely response to the Office Action dated July 24, 2002, please amend the above-identified application as follows:

IN THE CLAIMS:

The claims are amended as follows:

5. (amended) A wiring substrate comprising: an insulating substrate having an opening; at least one electronic part disposed in the opening; and an embedding resin comprising a thermoplastic resin, an acid anhydride curing agent, a curing accelerator, and a filler, wherein the embedding resin shows a viscosity of not higher than $85 \text{ Pa} \cdot \text{s}$ in a shear rate of 8.4 s^{-1} after being allowed to stand for 24 hours at $25^\circ\text{C} \pm 1^\circ\text{C}$, wherein the at least one electronic part is embedded with the embedding resin.

msb
Q1